



2024 IEEE REPP SYMPOSIUM



2024 IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)

November 7-8, 2024, hosted at Purdue University, West Lafayette, Indiana USA

2024 General Chair: Prof. Tiwei Wei, Purdue University
2024 Technical Program Chair: Farnood Rezaie, Cisco Systems

Session 1. Reliability for Thermal, Mechanical and Cooling Systems

Day 1: November 7, 2024

Time: 8:00 AM – 11:45 AM



Prof. Patrick McCluskey
University of Maryland



Prof. Amy Marconnet
Purdue University



Dr. Amr Haggag
ARM



Dr. Sreekant Narumanchi
National Renewable Energy
Laboratory



Prof. Srikanth Rangarajan
Binghamton University



Dr. Ryan Enright
Seguente



Dr. Alexander Hillström
Mälardalen University

2024 IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)

November 7-8, 2024, hosted at Purdue University, West Lafayette, Indiana USA

2024 General Chair: Prof. Tiwei Wei, Purdue University

2024 Technical Program Chair: Farnood Rezaie, Cisco Systems

Session 2. Reliability for Analog/RF and Power Integrated Circuits

Day 1: November 7, 2024.

Time: 12:45 PM – 5:35 PM



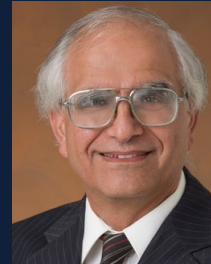
Dr. Alexander Grill
IMEC



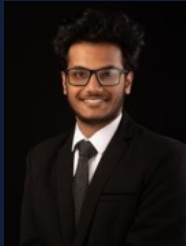
Kaiying Jiang
Stanford University



Prof. Luigi Balestra
University of Bologna



Dr. Reza Ghaffarian
Jet Propulsion Laboratory
California Institute of
Technology



Pranay Nagrani
Purdue University



Joaquin Matres
Google-X /
GDSFactory



Ritwik Kulkarni
Purdue University Samsung Advanced
Packaging



Dr. Yan Li



**Prof. Shubhra
Bansal**
Purdue University

2024 IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)

November 7-8, 2024, hosted at Purdue University, West Lafayette, Indiana USA

2024 General Chair: Prof. Tiwei Wei, Purdue University
2024 Technical Program Chair: Farnood Rezaie, Cisco Systems

Session 3. Reliability for Photonics

Day 2: November 8, 2024

Time: 8:00 AM – 12:15 PM



**Dr. Surya
Bhattacharya**
A*STAR Institute of
Microelectronics (IME)



**Prof. Vanessa
Smet**
Georgia Institute
of Technology



Yifan Yao
City University
of Hong Kong



Dr. David Coenen
IMEC



**Prof. Ganesh
Subbarayan**
Purdue University



**Dr. Xiaorong
Xiong**
Intel



**Dr. Jason
Zhang**
Intel



Shuhang Lyu
Purdue
University



**Dr. Oguzhan
Orkut Okudur**
IMEC



**Dr. Mario
Gonzalez**
IMEC

2024 IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)

November 7-8, 2024, hosted at Purdue University, West Lafayette, Indiana USA

2024 General Chair: Prof. Tiwei Wei, Purdue University
2024 Technical Program Chair: Farnood Rezaie, Cisco Systems

Session 4. Reliability, Metrology for Advanced Packaging, 3D Interconnects, in AI, HPC

Day 2: November 8, 2024

Time: 1:15 PM – 5:00 PM



Prof. Abhijit Dasgupta
University of Maryland



Prof. Bill King
University of Illinois –
Urbana-Champaign



Prof. David Huitink
University of Arkansas



Prof. Gabor Harsanyi
Budapest University of
Technology and Economics



Prof. Yoonjin Won
University of
California – Irvine



Michael Blattau
Ansys



**Jack (Kai-chieh)
Chiang**
Purdue University



Zhenliang Pan
Purdue University